



Material Content Data Sheet



Sales Product Name		BSS223PW H6327		Issued		1. August 2018		
MA#		MA002581182						
Package		PG-SOT323-3-3		Weight*		5.96 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	non noble metal	tin	7440-31-5	0.001	0.02		208	
	noble metal	gold	7440-57-5	0.005	0.08		807	
	inorganic material	silicon	7440-21-3	0.055	0.91	1.01	9144	10159
leadframe	inorganic material	silicon	7440-21-3	0.001	0.01		88	
	non noble metal	titanium	7440-32-6	0.003	0.04		441	
	non noble metal	chromium	7440-47-3	0.008	0.13		1322	
	non noble metal	copper	7440-50-8	2.617	43.90	44.08	438874	440725
wire	non noble metal	copper	7440-50-8	0.005	0.08	0.08	837	837
encapsulation	organic material	carbon black	1333-86-4	0.031	0.52		5244	
	plastics	epoxy resin	-	0.672	11.27		112734	
	inorganic material	silicondioxide	60676-86-0	2.423	40.64	52.43	406368	524346
leadfinish	non noble metal	tin	7440-31-5	0.133	2.23	2.23	22254	22254
plating	noble metal	silver	7440-22-4	0.010	0.17	0.17	1679	1679
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com